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Intel - EPM7160STC100-6N Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	6 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	10
Number of Macrocells	160
Number of Gates	3200
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7160stc100-6n

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

	 Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest Programming support Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices
General Description	The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) <i>PCI Local Bus Specification, Revision 2.2.</i> See Table 3 for available speed grades.

Device					Speed	Grade				
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		>	~		>		>	~	 	
EPM7032S	\checkmark	\checkmark	~		 Image: A start of the start of					
EPM7064		>	~		>		>	~		
EPM7064S	\checkmark	\checkmark	~		 Image: A start of the start of					
EPM7096			\checkmark		\checkmark		>	\checkmark		
EPM7128E			~	\checkmark	 Image: A start of the start of		>	~		~
EPM7128S		\checkmark	~		 Image: A start of the start of			~		
EPM7160E				~	~		\checkmark	~		\checkmark
EPM7160S		\checkmark	~		 Image: A start of the start of			~		
EPM7192E						~	>	~		>
EPM7192S			~	1	~	Ī		~		
EPM7256E						~	>	~		>
EPM7256S			\checkmark		\checkmark			\checkmark		

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and highspeed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)— and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

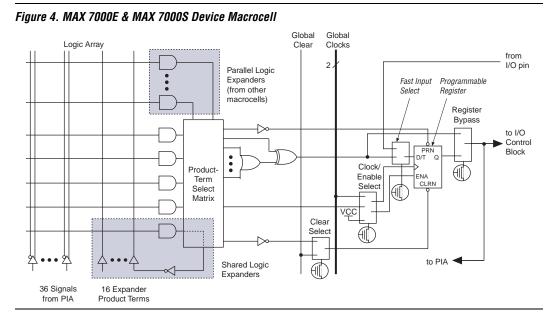
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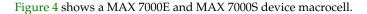
For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks





Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

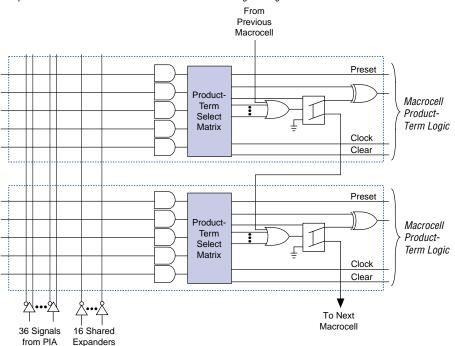
- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization. The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lowernumbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

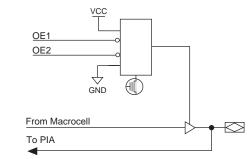
Figure 6. Parallel Expanders



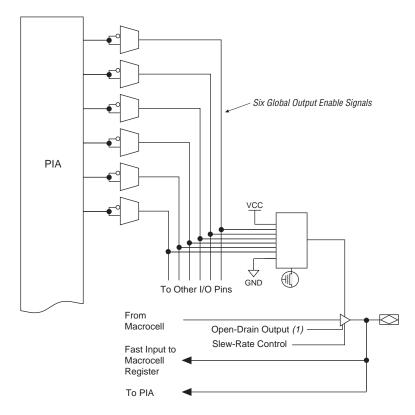
Unused product terms in a macrocell can be allocated to a neighboring macrocell.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices







Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , \mathbf{t}_{ACL} , and \mathbf{t}_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1} .

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

devices.

Figure 9 shows the timing requirements for the JTAG signals.

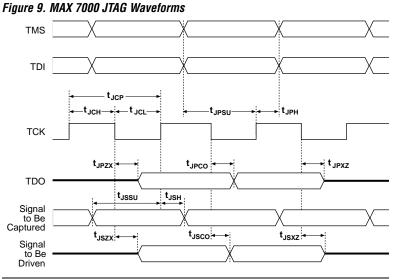


Table 12 shows the JTAG timing parameters and values for MAX 7000S

Table 1	Table 12. JTAG Timing Parameters & Values for MAX 7000S Devices										
Symbol	Parameter	Min	Мах	Unit							
t _{JCP}	TCK clock period	100		ns							
t _{JCH}	TCK clock high time	50		ns							
t _{JCL}	TCK clock low time	50		ns							
t _{JPSU}	JTAG port setup time	20		ns							
t _{JPH}	JTAG port hold time	45		ns							
t _{JPCO}	JTAG port clock to output		25	ns							
t _{JPZX}	JTAG port high impedance to valid output		25	ns							
t _{JPXZ}	JTAG port valid output to high impedance		25	ns							
t _{JSSU}	Capture register setup time	20		ns							
t _{JSH}	Capture register hold time	45		ns							
t _{JSCO}	Update register clock to output		25	ns							
t _{JSZX}	Update register high impedance to valid output		25	ns							
t _{JSXZ}	Update register valid output to high impedance		25	ns							



For more information, see *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*).

Operating Conditions

Tables 13 through 18 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

Table 13. MAX 7000 5.0-V Device Absolute Maximum Ratings Note (1)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply voltage	With respect to ground (2)	-2.0	7.0	V
VI	DC input voltage		-2.0	7.0	V
I _{OUT}	DC output current, per pin		-25	25	mA
T _{STG}	Storage temperature	No bias	-65	150	°C
T _{AMB}	Ambient temperature	Under bias	-65	135	°C
TJ	Junction temperature	Ceramic packages, under bias		150	°C
		PQFP and RQFP packages, under bias		135	°C

Table 1	Table 14. MAX 7000 5.0-V Device Recommended Operating Conditions								
Symbol	Parameter	Conditions	Min	Мах	Unit				
V _{CCINT}	Supply voltage for internal logic and input buffers	(3), (4), (5)	4.75 (4.50)	5.25 (5.50)	V				
V _{CCIO}	Supply voltage for output drivers, 5.0-V operation(3), (4)	(3), (4)	4.75 (4.50)	5.25 (5.50)	V				
	Supply voltage for output drivers, 3.3-V operation	(3), (4), (6)	3.00 (3.00)	3.60 (3.60)	V				
V _{CCISP}	Supply voltage during ISP	(7)	4.75	5.25	V				
VI	Input voltage		-0.5 (8)	V _{CCINT} + 0.5	V				
Vo	Output voltage		0	V _{CCIO}	V				
T _A	Ambient temperature	For commercial use	0	70	°C				
		For industrial use	-40	85	°C				
TJ	Junction temperature	For commercial use	0	90	°C				
		For industrial use	-40	105	°C				
t _R	Input rise time			40	ns				
t _F	Input fall time			40	ns				

Table 15. MAX 7000 5.0-V Device DC Operating Conditions Note (9)								
Symbol	Parameter	Conditions	Min	Max	Unit			
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V			
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V			
V _{OH}	5.0-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V} (10)$	2.4		V			
	3.3-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V} (10)$	2.4		V			
	3.3-V high-level CMOS output voltage	I_{OH} = -0.1 mA DC, V_{CCIO} = 3.0 V (10)	V _{CCIO} – 0.2		V			
V _{OL}	5.0-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 4.75 V (11)		0.45	V			
	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)		0.45	V			
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.0 V(11)		0.2	V			
I _I	Leakage current of dedicated input pins	$V_{I} = -0.5$ to 5.5 V (11)	-10	10	μΑ			
I _{OZ}	I/O pin tri-state output off-state current	V _I = -0.5 to 5.5 V (11), (12)	-40	40	μA			

Table 1	Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices Note (13)							
Symbol	Parameter	Conditions	Min	Max	Unit			
CIN	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF			
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF			

Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices Note (13)							
Symbol	Parameter	Conditions	Min	Max	Unit		
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF		
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF		

Table 1	Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
CIN	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF					

.

Symbol	Parameter	Conditions	Speed	Grade -6	Speed Grade -7		Unit
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.4		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t _{FIN}	Fast input delay	(2)		0.8		1.0	ns
t _{SEXP}	Shared expander delay			3.5		4.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			2.0		3.0	ns
t _{LAC}	Logic control array delay			2.0		3.0	ns
t _{IOE}	Internal output enable delay	(2)				2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 5.0 V$	C1 = 35 pF		2.0		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF (7)		2.5		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on, $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		7.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 5.0 V$	C1 = 35 pF		4.0		4.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF (7)		4.5		4.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t _{SU}	Register setup time		3.0		3.0		ns
t _H	Register hold time		1.5		2.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			0.8		1.0	ns
t _{COMB}	Combinatorial delay			0.8		1.0	ns
t _{IC}	Array clock delay			2.5		3.0	ns
t _{EN}	Register enable time			2.0		3.0	ns
t _{GLOB}	Global control delay			0.8		1.0	ns
t _{PRE}	Register preset time			2.0		2.0	ns
t _{CLR}	Register clear time			2.0		2.0	ns
t _{PIA}	PIA delay			0.8		1.0	ns
t _{LPA}	Low-power adder	(8)		10.0		10.0	ns

Table 2	21. MAX 7000 & MAX 7000E Ext	ernal Timing Parame	eters Note	(1)				
Symbol	Parameter	Conditions		Speed Grade				
			MAX 700	MAX 7000E (-10P)		00 (-10) Doe (-10)		
			Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t _{SU}	Global clock setup time		7.0		8.0		ns	
t _H	Global clock hold time		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns	
t _{CH}	Global clock high time		4.0		4.0		ns	
t _{CL}	Global clock low time		4.0		4.0		ns	
t _{ASU}	Array clock setup time		2.0		3.0		ns	
t _{AH}	Array clock hold time		3.0		3.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns	
t _{ACH}	Array clock high time		4.0		4.0		ns	
t _{ACL}	Array clock low time		4.0		4.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns	
t _{CNT}	Minimum global clock period			10.0		10.0	ns	
f _{CNT}	Maximum internal global clock frequency	(5)	100.0		100.0		MHz	
t _{ACNT}	Minimum array clock period			10.0		10.0	ns	
f _{acnt}	Maximum internal array clock frequency	(5)	100.0		100.0		MHz	
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade		Unit		
			-	5	-	6	-7			-10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{odh}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 2	8. EPM7032S Internal T	iming Parameter	rs A	lote (1)							
Symbol	mbol Parameter Conditions Speed Grade							Unit			
			-	5	-	6	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade	ade					
			-	5	-	6	-	7	-1	0			
			Min	Max	Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns		
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns		
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns		
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns		
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns		

Table 3	0. EPM7064S Internal Tir	ning Parameters	s (Part à	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions			Speed Grade						
			-	5	-	6	-	7	-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns
t _{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns
t _{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter (2) must be added to this minimum width if the clear or reset signal incorporates the t_{IAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- The f_{MAX} values represent the highest frequency for pipelined data. (5)
- Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use. (6)
- For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, (7) these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells (8) running in the low-power mode.

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-	6	-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns
t _{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF <i>(3)</i>	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f _{сnт}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

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Symbol	Parameter	Conditions			Speed	Grade	Unit		
			-	7	-10		-15		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.9		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.8		2.0		4.0		ns
t _{AH}	Array clock hold time		1.9		3.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			7.8		10.0		13.0	ns
fcnt	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			7.8		10.0		13.0	ns
f _{acnt}	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz

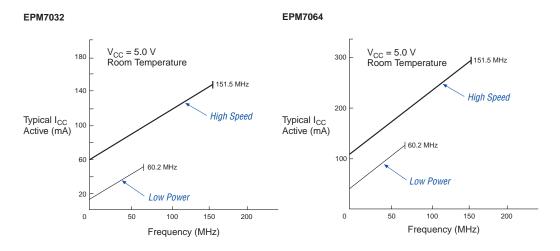
Tables 37 and 38 show the EPM7256S AC operating conditions.

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	7	-1	10	-1	5	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t _{FIN}	Fast input delay			3.4		1.0		2.0	ns
t _{SEXP}	Shared expander delay			3.9		5.0		8.0	ns
t _{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns
t _{LAD}	Logic array delay			2.6		5.0		6.0	ns
t _{LAC}	Logic control array delay			2.6		5.0		6.0	ns
t _{IOE}	Internal output enable delay			0.8		2.0		3.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t _{SU}	Register setup time		1.1		2.0		4.0		ns
t _H	Register hold time		1.6		3.0		4.0		ns
t _{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns
t _{FH}	Register hold time of fast input		0.6		0.5		1.0		ns
t _{RD}	Register delay			1.1		2.0		1.0	ns
t _{COMB}	Combinatorial delay			1.1		2.0		1.0	ns
t _{IC}	Array clock delay			2.9		5.0		6.0	ns
t _{EN}	Register enable time			2.6		5.0		6.0	ns
t _{GLOB}	Global control delay			2.8		1.0		1.0	ns
t _{PRE}	Register preset time			2.7		3.0		4.0	ns
t _{CLR}	Register clear time			2.7		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		3.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns

Table 39. MAX 7000 I _{CC} Equation Constants									
Device	A	В	C						
EPM7032	1.87	0.52	0.144						
EPM7064	1.63	0.74	0.144						
EPM7096	1.63	0.74	0.144						
EPM7128E	1.17	0.54	0.096						
EPM7160E	1.17	0.54	0.096						
EPM7192E	1.17	0.54	0.096						
EPM7256E	1.17	0.54	0.096						
EPM7032S	0.93	0.40	0.040						
EPM7064S	0.93	0.40	0.040						
EPM7128S	0.93	0.40	0.040						
EPM7160S	0.93	0.40	0.040						
EPM7192S	0.93	0.40	0.040						
EPM7256S	0.93	0.40	0.040						

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions. Figure 14 shows typical supply current versus frequency for MAX 7000 devices.





EPM7096

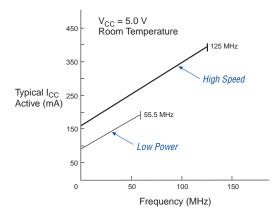


Figure 15 shows typical supply current versus frequency for MAX 7000S devices.

